



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-20
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Representative Email *	Refer to Supplier Comment section		
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST715PUR	MY59*UL56J51	A	SA1A	2016-06-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	20.66	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X1.0	12	No lead	
Comment	VFDFPN 8 3x3x1.0 PITCH 0.65 SAWN			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	MY59*UL56J51					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.380	mg	supplier	die	Silicon (Si)	7440-21-3		0.380	mg	1000000	18390
Leadframe	Copper & its alloys	9.412	mg	supplier	alloy	Copper	7440-50-8		9.070	mg	976109	438949
				supplier	alloy	Iron	7439-89-6		0.210	mg	22600	10163
				supplier	alloy	Phosphorus	12185-10-3		0.002	mg	215	97
				supplier	alloy	Zinc	7440-66-6		0.010	mg	1076	484
				supplier	metallization	Nickel	7440-02-0		0.110	mg	916667	5324
				supplier	metallization	Palladium	7440-05-3		0.009	mg	75000	436
Die attach	Other inorganic materials	0.031	mg	supplier	metallization	Gold	7440-57-5		0.001	mg	8333	48
				supplier	glue	Silver (Ag)	7440-22-4		0.021	mg	677419	1016
				supplier	glue	Methylene diacrylate	42594-17-2		0.008	mg	258065	387
				supplier	glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.001	mg	32258	48
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.001	mg	32258	48
Bonding wires	Other inorganic materials	0.100	mg	supplier	wire	Gold (Au)	7440-57-5		0.100	mg	1000000	4840
Encapsulation	Other Organic Materials	10.740	mg	supplier	mold compound	Silica, vitreous	60676-86-0		9.945	mg	925978	481295
				supplier	mold compound	Epoxy resin	85954-11-6		0.430	mg	40037	20810
				supplier	mold compound	Phenol resin	26834-02-6		0.322	mg	29981	15583
				supplier	mold compound	Carbon black	1333-86-4		0.043	mg	4004	2081